



## Product Change Notification / MAAN-23YDQH871

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### Date:

14-May-2024

### Product Category:

FPGA Configuration Memory

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 6653 Final Notice: Qualification of G700LS as new mold compound material for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC (.300in) package with MSL 3 classification.

### Affected CPNs:

[MAAN-23YDQH871\\_Affected\\_CPN\\_05142024.pdf](#)  
[MAAN-23YDQH871\\_Affected\\_CPN\\_05142024.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of G700LS as new mold compound material for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC (.300in) package with MSL 3 classification.

### Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Technology	Amkor Technology

	Philippine (P1/P2), INC. (ANAP)	Philippine (P1/P2), INC. (ANAP)
Wire Material	Au	Au
Die Attach Material	8290	8290
Molding Compound Material	G600	G700LS
Lead-Frame Material	C194	C194
Lead-Frame Design	See Pre and Post change comparison	
Moisture Sensitivity Level (MSL)	MSL 1	MSL 3

**Impacts to Data Sheet:**None

**Change Impact**None

**Reason for Change:**To improve manufacturability by qualifying G700LS as new molding compound material.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**June 30, 2024 (date code: 2427)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	October 2023					>	May 2024					June 2024				
Workweek	40	41	42	43	44		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date				x												
Qual Report Availability									x							
Final PCN Issue Date									x							
Estimated Implementation Date																x

**Method to Identify Change:**

Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as

PCN\_#\_Qual\_Report.

**Revision History:**October 25, 2023: Issued initial notification.

May 14, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 30, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_MAAN-23YDQH871\\_Qual\\_Report.pdf](#)

[PCN\\_MAAN-23YDQH871\\_Pre\\_and\\_Post\\_Change\\_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT17LV002-10SU